

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the present application:

LISTING OF CLAIMS:

Claims 1-22. (Canceled).

23. (Currently Amended) A rectifier for rectifying an alternating current into a direct current, comprising:

a control part including a controller component and control terminals;

a power circuit controlled by the control part and including switching elements, wherein the control part is spatially separate from the power circuit; and

a three-phase generator including a three-phase stator winding, wherein:

phases of the stator winding are triggered via the switching elements,

all power-conducting components of the power circuit are power MOS components and are integrated in a stacked construction.

24. (Previously Presented) The rectifier as recited in Claim 23, wherein the power-conducting components are power MOS components that are contacted on both sides.

25. (Currently Amended) The rectifier as recited in Claim 23, further comprising:

a cooling device, wherein:

the stacked construction of the power circuit includes a first substrate and a second substrate, between which the power MOS components are placed via contacts on both sides.

26. (Previously Presented) The rectifier as recited in Claim 25, wherein the cooling device is situated on top of the stacked construction.

27. (Previously Presented) The rectifier as recited in Claim 25, wherein the cooling device is situated on the bottom of the stacked construction.

28. (Previously Presented) The rectifier as recited in Claim 23, wherein the power circuit is contacted outward over a surface.

29. (Previously Presented) The rectifier as recited in Claim 28, wherein the power circuit is contacted outward via a heat conducting paste applied over a surface for dissipating heat.

30. (Previously Presented) The rectifier as recited in Claim 24, wherein the power MOS components are contacted on both sides via contact surfaces serving as soldering points/soldering surfaces in the stacked construction.

31. (Previously Presented) The rectifier as recited in Claim 24, wherein the power MOS components are contacted on both sides via contact surfaces serving as conductive adhesive surfaces in the stacked construction.

32. (Previously Presented) The rectifier as recited in Claim 24, further comprising:
a cooling element, wherein the stacked construction of the power circuit includes a pressed screen and a first substrate, between which the power MOS components, contacted on both sides, are placed.

33. (Previously Presented) The rectifier as recited in Claim 23, wherein the stacked construction of the power circuit includes an IMS substrate, to which the power MOS components are connected.

34. (Previously Presented) The rectifier as recited in Claim 23, wherein the control part is designed in a single-chip construction and includes a controller-ASIC component having an integrated driver component.

35. (Previously Presented) The rectifier as recited in Claim 23, wherein the control part is designed in a multi-chip construction having a separate controller-ASIC component and a separate driver component .

36. (Previously Presented) The rectifier as recited in Claim 25, wherein the power circuit contains power terminals as contacts between the first substrate and the second substrate.

37. (Previously Presented) The rectifier as recited in Claim 25, wherein the power circuit includes power terminals that are placed on the first substrate of the stacked construction.

38. (Previously Presented) The rectifier as recited in Claim 23, further comprising:
an injection molded material in which the power MOS components are encapsulated.

39. (Previously Presented) The rectifier as recited in Claim 25, wherein power terminals of the power circuit extend outside on an exposed, coating-free surface of one of substrate surfaces of the stacked construction.

40. (Previously Presented) The rectifier as recited in Claim 38, wherein the power terminals extend one of outside laterally and in a vertical direction from the power circuit.

41. (Previously Presented) The rectifier as recited in Claim 23, wherein:
the control part is situated on a surface, made from injection molded material, of the power circuit and is connected thereto via the control terminals extending outside in a vertical direction.

42. (Previously Presented) The rectifier as recited in Claim 23, wherein the control part includes an application-specific element.

43. (Previously Presented) The rectifier as recited in Claim 25, wherein the stacked construction includes a base plate having metallic fixing elements projecting from sides thereof.

44. (Previously Presented) The rectifier as recited in Claim 25, wherein the control part includes one of a standard-packaged IC and an IC having a wiring, each having

second control terminals and to which the control terminals of one of the first substrate and the second substrate are connected.